

1:10 Differential LVDS Fanout Buffer

Features

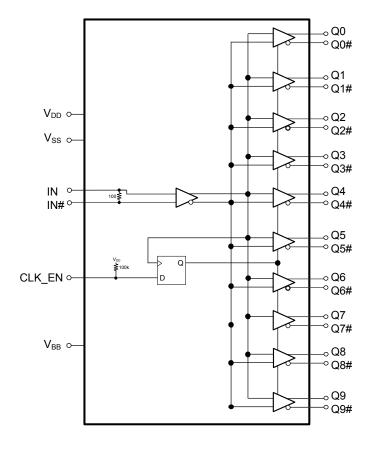
- Low-voltage differential signal (LVDS) input with on-chip 100 Ω input termination resistor
- Ten differential LVDS outputs
- 40 ps maximum output-to-output skew
- 600 ps maximum propagation delay
- 0.11 ps maximum additive RMS phase jitter at 156.25 MHz (12 kHz to 20 MHz offset)
- Up to 1.5 GHz operation
- Synchronous clock enable function
- 32-pin thin quad flat pack (TQFP) package
- 2.5 V or 3.3 V operating voltage [1]
- Commercial and industrial operating temperature range

Functional Description

The CY2DL1510 is an ultra-low noise, low-skew, low-propagation delay 1:10 differential LVDS fanout buffer targeted to meet the requirements of high-speed clock distribution applications. The on-chip 100 Ω input termination resistor reduces board component count, while the synchronous clock enable function ensures glitch-free output transitions during enable and disable periods. The device has a fully differential internal architecture that is optimized to achieve low-additive jitter and low-skew at operating frequencies of up to 1.5 GHz

For a complete list of related documentation, click here.

Logic Block Diagram



Note

1. Input AC-coupling capacitors are required for voltage-translation applications.



Contents

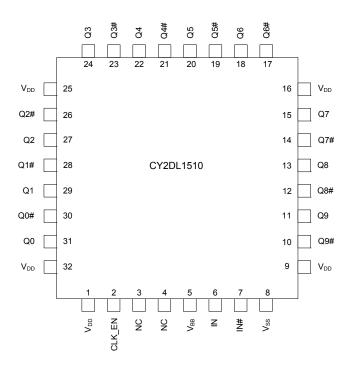
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Pinouts

Figure 1. 32-pin TQFP pinout



Pin Definitions

Pin No.	Pin Name	Pin Type	Description
1, 9, 16, 25, 32	V_{DD}	Power	Power supply
2	CLK_EN	Input	Synchronous clock enable. Low-voltage complementary metal oxide semiconductor (LVCMOS)/low-voltage transistor-transistor-logic (LVTTL). When CLK_EN = Low, Q(0:9) outputs are held low and Q(0:9)# outputs are held high
3, 4	NC		No connection
5	V _{BB}	Output	LVDS reference voltage output
6	IN	Input	LVDS input clock
7	IN#	Input	LVDS complementary input clock
8	V _{SS}	Power	Ground
10, 12, 14, 17, 19, 21, 23, 26, 28, 30	Q(0:9)#	Output	LVDS complementary output clocks
11, 13, 15, 18, 20, 22, 24, 27, 29, 31	Q(0:9)	Output	LVDS output clocks



Absolute Maximum Ratings

Parameter	Description	Condition	Min	Max	Unit
V_{DD}	Supply voltage	Non-functional	-0.5	4.6	V
V _{IN} ^[2]	Input voltage, relative to V _{SS}	Non-functional	-0.5	lesser of 4.0 or V _{DD} + 0.4	V
V _{OUT} ^[2]	DC output or I/O Voltage, relative to V _{SS}	Non-functional	-0.5	lesser of 4.0 or V _{DD} + 0.4	V
T _S	Storage temperature	Non-functional	-55	150	°C
ESD _{HBM}	Electrostatic discharge (ESD) protection (Human body model)	JEDEC STD 22-A114-B	2000	_	V
L _U	Latch up		Meets or exc JESD78E	ceeds JEDEC 3 IC latch up	
UL-94	Flammability rating	At 1/8 in.		V-0	
MSL	Moisture sensitivity level			3	

Operating Conditions

Parameter	Description	Condition	Min	Max	Unit
V_{DD}	Supply voltage	2.5 V supply	2.375	2.625	V
		3.3 V supply	3.135	3.465	V
T _A	Ambient operating temperature	Commercial	0	70	°C
		Industrial	-40	85	°C
t _{PU}	Power ramp time	Power-up time for V _{DD} to reach minimum specified voltage (power ramp must be monotonic.)	0.05	500	ms

Note
2. The voltage on any I/O pin cannot exceed the power pin during power-up. Power supply sequencing is not required.



DC Electrical Specifications

 $(V_{DD}$ = 3.3 V ± 5% or 2.5 V ± 5%; T_A = 0 °C to 70 °C (Commercial) or –40 °C to 85 °C (Industrial))

Parameter	Description	Condition	Min	Max	Unit
I _{DD}	Operating supply current	All LVDS outputs terminated with 100 Ω load [3, 4]	_	125	mA
V _{IH1}	Input high Voltage, LVDS input clocks, IN and IN#		_	V _{DD} + 0.3	V
V_{IL1}	Input low voltage, LVDS input clocks, IN and IN#		-0.3	_	V
V_{IH2}	Input high voltage, CLK_EN	V _{DD} = 3.3 V	2.0	$V_{DD} + 0.3$	V
V_{IL2}	Input low voltage, CLK_EN	V _{DD} = 3.3 V	-0.3	0.8	V
V _{IH3}	Input high voltage, CLK_EN	V _{DD} = 2.5 V	1.7	V _{DD} + 0.3	V
V _{IL3}	Input low voltage, CLK_EN	V _{DD} = 2.5 V	-0.3	0.7	V
V _{ID} ^[5]	Input differential amplitude	See Figure 3 on page 7	0.4	0.8	V
V _{ICM}	Input common mode voltage	See Figure 3 on page 7	0.5	V _{DD} – 0.2	V
I _{IH}	Input high current, All inputs	Input = V _{DD} [6]	_	150	μΑ
I _{IL}	Input low current, All inputs	Input = V _{SS} [6]	-150	_	μΑ
V _{PP}	LVDS differential output voltage peak to peak, single-ended	V_{DD} = 3.3 V or 2.5 V, R_{TERM} = 100 Ω between Q and Q# pairs [3, 7]	250	470	mV
ΔV_{OCM}	Change in V _{OCM} between complementary output states	V_{DD} = 3.3 V or 2.5 V, R _{TERM} = 100 Ω between Q and Q# pairs [3, 7]	_	50	mV
V_{BB}	Output reference voltage	0 to 150 μA output current	1.125	1.375	V
R _{TERM}	On-chip differential input termination resistor		80	120	Ω
R _P	Internal pull-up resistance, LVCMOS logic input	CLK_EN pin	60	140	kΩ
C _{IN}	Input capacitance	Measured at 10 MHz per pin	_	3	pF

- Refer to Figure 2 on page 7.
 I_{DD} includes current that is dissipated externally in the output termination resistors.
 V_{ID} minimum of 400 mV is required to meet all output AC Electrical Specifications. The device is functional with V_{ID} minimum of greater than 200 mV.
 Positive current flows into the input pin, negative current flows out of the input pin.
 Refer to Figure 4 on page 7.



AC Electrical Specifications

(V_{DD} = 3.3 V \pm 5% or 2.5 V \pm 5%; T_A = 0 °C to 70 °C (Commercial) or –40 °C to 85 °C (Industrial))

Parameter	Description	Condition	Min	Тур	Max	Unit
F _{IN}	Input frequency		DC	_	1.5	GHz
F _{OUT}	Output frequency	F _{OUT} = F _{IN}	DC	_	1.5	GHz
t _{PD} ^[10]	Propagation delay input pair to output pair	Input rise/fall time < 1.5 ns (20% to 80%)	_	-	600	ps
t _{ODC} ^[11]	Output duty cycle	50% duty cycle at input Frequency range up to 1 GHz	48	-	52	%
t _{SK1} ^[12]	Output-to-output skew	Any output to any output, with same load conditions at DUT	-	_	40	ps
t _{SK1 D} ^[12]	Device-to-device output skew	Any output to any output between two or more devices. Devices must have the same input and have the same output load.	-	_	150	ps
PN _{ADD}	Additive RMS phase noise 156.25 MHz input	Offset = 1 kHz	_	-	-120	dBc/ Hz
	Rise/fall time < 150 ps (20% to 80%) V _{ID} > 400 mV	Offset = 10 kHz	-	-	-135	dBc/ Hz
	VID > 400 IIIV	Offset = 100 kHz	-	_	-135	dBc/ Hz
		Offset = 1 MHz	-	_	-150	dBc/ Hz
		Offset = 10 MHz	-	-	-154	dBc/ Hz
		Offset = 20 MHz	-	-	-155	dBc/ Hz
t _{JIT} ^[13]	Additive RMS phase jitter (Random)	156.25 MHz, 12 kHz to 20 MHz offset; input rise/fall time < 150 ps (20% to 80%), V _{ID} > 400 mV	-	-	0.11	ps
t _R , t _F ^[14]	Output rise/fall time, single-ended	50% duty cycle at input, 20% to 80% of full swing (V _{OL} to V _{OH}) Input rise/fall time < 1.5 ns (20% to 80%) Measured at 1 GHz	-	_	300	ps
t _{SOD}	Time from clock edge to outputs disabled	Synchronous clock enable (CLK_EN) switched low	-	_	700	ps
t _{SOE}	Time from clock edge to outputs enabled	Synchronous clock enable (CLK_EN) switched high	-	_	700	ps

Notes

^{8.} Refer to Figure 2 on page 7.
9. Refer to Figure 4 on page 7.
10. Refer to Figure 5 on page 7.
11. Refer to Figure 6 on page 7.
12. Refer to Figure 7 on page 8.
13. Refer to Figure 8 on page 8.

^{14.} Refer to Figure 9 on page 8.



Switching Waveforms

Figure 2. LVDS Output Termination

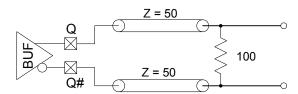


Figure 3. Input Differential and Common Mode Voltages

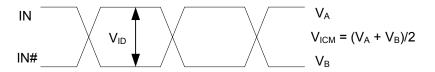


Figure 4. Output Differential and Common Mode Voltages



Figure 5. Input to Any Output Pair Propagation Delay

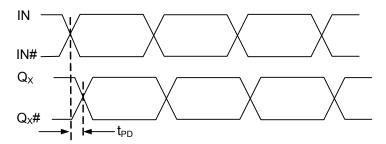
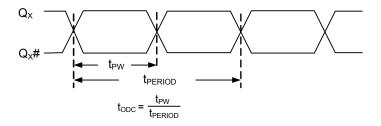


Figure 6. Output Duty Cycle





Switching Waveforms (continued)

Figure 7. Output-to-output and Device-to-device Skew

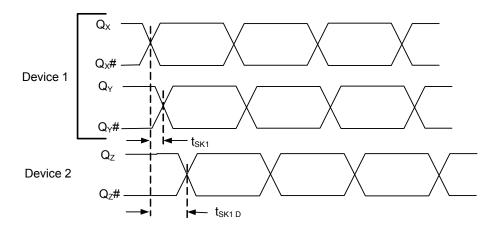


Figure 8. RMS Phase Jitter

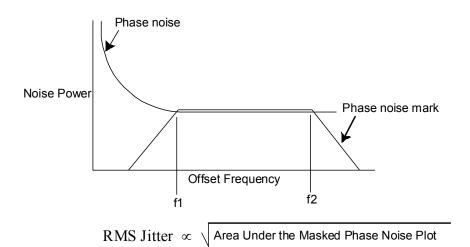
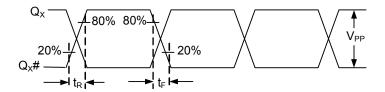


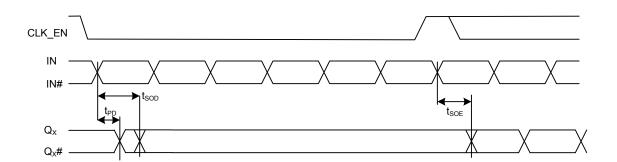
Figure 9. Output Rise/Fall Time





Switching Waveforms (continued)

Figure 10. Synchronous Clock Enable Timing

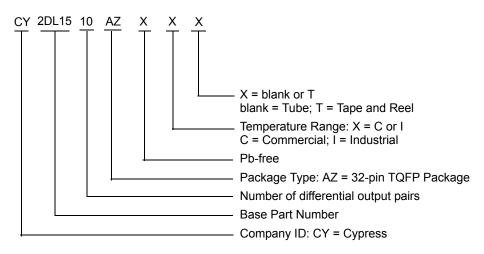




Ordering Information

Part Number	Туре	Production Flow	
Pb-free			
CY2DL1510AZC	32-pin TQFP	Commercial, 0 °C to 70 °C	
CY2DL1510AZCT	32-pin TQFP – Tape and Reel	Commercial, 0 °C to 70 °C	
CY2DL1510AZI	32-pin TQFP	Industrial, –40 °C to 85 °C	
CY2DL1510AZIT	32-pin TQFP – Tape and Reel	Industrial, –40 °C to 85 °C	

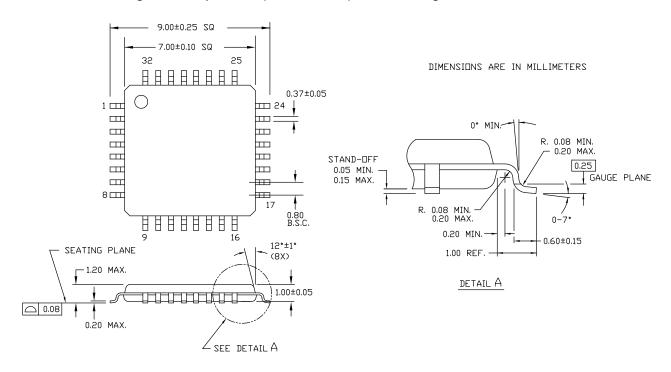
Ordering Code Definitions





Package Diagram

Figure 11. 32-pin TQFP (7 × 7 × 1.0 mm) A 3210 Package Outline, 51-85063



51-85063 *D



Acronyms

Acronym	Description			
ESD	Electrostatic Discharge			
HBM	Human Body Model			
JEDEC	Joint Electron Devices Engineering Council			
LVDS	Low-Voltage Differential Signal			
LVCMOS	Low-Voltage Complementary Metal Oxide Semiconductor			
LVTTL	Low-Voltage Transistor-Transistor Logic			
OE	Output Enable			
RMS	Root Mean Square			
TQFP	Thin Quad Flat Pack			

Document Conventions

Units of Measure

Symbol	Unit of Measure			
°C	degree Celsius			
dBc	decibels relative to the carrier			
GHz	gigahertz			
Hz	hertz			
kΩ	kilohm			
MHz	megahertz			
μΑ	microampere			
μF	microfarad			
μs	microsecond			
mA	milliampere			
ms	millisecond			
mV	millivolt			
ns	nanosecond			
Ω	ohm			
pF	picofarad			
ps	picosecond			
V	volt			
W	watt			



Document History Page

	Document Title: CY2DL1510, 1:10 Differential LVDS Fanout Buffer Document Number: 001-54863					
Revision	ECN	Orig. of Change	Submission Date	Description of Change		
**	2744225	CXQ / PYRS	08/19/09	New data sheet.		
*A	2782891	CXQ	10/09/09	Updated format of Logic Block Diagram on page 1. Added T _{SOD} and T _{SOE} specs (700 ps max) to AC Specs table. Added T _{SETUP} and T _{HOLD} specs (300 ps min) to AC Specs table. Changed equation for RMS jitter in Figure 8 to proportionality. Changed package drawing from 1.4 mm thickness 51-85088 spec to 1.0 mm thickness 51-850063 spec. Added "Synchronous Clock Enable Function" to Features on page 1.		
*B	2838916	CXQ	01/05/2010	Changed status from "ADVANCE" to "PRELIMINARY". Changed from 0.34 ps to 0.25 ps maximum additive jitter in "Features" on page 1 and in t_{JIT} in the AC Electrical Specs table on page 5. Added t_{PU} spec to the Operating Conditions table on page 3. Removed V_{OD} and ΔV_{OD} specs from the DC Electrical Specs table on page 4. Added V_{PP} and ΔV_{PP} specs to the AC Electrical Specs table on page 5. V_{PP} min = 250 mV and max = 470 mV; ΔV_{PP} max = 50 mV. Added internal pullup resistance spec for CLK_EN in the DC Electrical Specs table on page 4. Min = 60 k Ω , Max = 140 k Ω . Added a measurement definition for C_{IN} in the DC Electrical Specs table on page 4. Changed letter case and some names of all the timing parameters in the AC Electrical Specs table on page 5 to be consistent with EROS. Lowered all additive phase noise mask specs by 3 dB in the AC Electrical Specs table on page 5. Added condition to t_R and t_F specs in the AC Electrical specs table on page 5 that input rise/fall time must be less than 1.5 ns (20% to 80%). Changed letter case and some names of all the timing parameters in Figures 5, 6, 7, and 9, to be consistent with EROS. Updated Figure 4 with definitions for V_{PP} and ΔV_{PP}		
*C	2885033	CXQ	02/26/2010	Updated 32-Pin TQFP package diagram.		
*D	3011766	CXQ	08/20/2010	Changed maximum additive jitter from 0.25 ps to 0.11 ps in "Features" on page 1 and in t_{JIT} in the AC Electrical Specs table on page 5. Changed max t_{PD} spec from 480 ps to 600 ps. Added note 5 to describe I_{IH} and I_{IL} specs. Removed reference to data distribution from "Functional Description". Changed R_P for differential inputs from 100 $k\Omega$ to 150 $k\Omega$ in the Logic Block Diagram and from 60 $k\Omega$ min / 140 $k\Omega$ max to 90 $k\Omega$ min / 210 $k\Omega$ max in the DC Electrical Specs table. Added V_{ID} max spec of 0.8V in the DC Electrical Specs table. Updated phase noise specs for 1 k/10 k/100 k/1 M/10 M/20 MHz offset to -120/-130/-135/-150/-150/-150dBc/Hz, respectively, in the AC Electrical Specs table. Added "Frequency range up to 1 GHz" condition to t_{ODC} spec. Added Acronyms and Ordering Code Definition.		
*E	3017258	CXQ	08/27/2010	Corrected Output Rise/Fall time diagram.		



Document History Page (continued)

	Document Title: CY2DL1510, 1:10 Differential LVDS Fanout Buffer Document Number: 001-54863						
Revision	ECN	Orig. of Change	Submission Date	Description of Change			
*F	3100234	CXQ	11/18/2010	Changed V_{IN} and V_{OUT} specs from 4.0V to "lesser of 4.0 or V_{DD} + 0.4" Removed 200mA min LU spec, replaced with "Meets or exceeds JEDEC Spec JESD78B IC Latchup Test" Moved V_{PP} from AC spec table to DC spec table, removed ΔV_{PP} Removed R_P spec for differential input clock pins IN_X and IN_X #. Changed C_{IN} condition to "Measured at 10 MHz". Changed PN _{ADD} specs for 10kHz, 10MHz, and 20MHz offsets. Added "Measured at 1 GHz" to t_R , t_F spec condition. Removed t_S and t_H specs from AC specs table. Changed to CY2DL1510AZ package code in Ordering Information. Added to Z package code in Ordering Code Definition.			
*G	3135201	CXQ	01/12/2011	Removed "Preliminary" status heading. Fixed typo and removed resistors from IN/IN# in Logic Block Diagram. Added Figure 10 to describe T _{SOE} and T _{SOD} .			
*H	3090938	CXQ	02/25/2011	Post to external web.			
*	3952187	CINM	04/02/2013	Updated Package Diagram: spec 51-85063 – Changed revision from *C to *D. Updated in new template. Completing sunset review.			
*J	4586288	CINM	12/04/2014	Added related documentation hyperlink in page 1.			



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